



# **Example list of results corresponding to a single layer film**

Film kind	ITO	αFTO	Cr	Al	Ni	Au	Cu	Ag	Ti	Мо	IZO	MAM	FTO
								(APC)					
Film thickness	20~	50~	10~	100~	100~	100~	100~	100	100	100	300	100	40~
unit nm	450	200	300	1000	500	500	2000				10Ω<	~500	800
Minimum pitch	6	6	6	10	10	20	20	20	20	20	20	20	2
unit μm													(mm)
Minimamu L/S	3/3	3/3	3/3	5/5	5/5	10/10	10/30	10/10	10/10	10/10	10/10	10/10	2/2
unit μm													(mm)
Forming accuracy	±1 μ	±1μ	±1 μ	±3 μ	±3 μ	±3μ	±5μ	±5μ	±3μ	±3μ	±3μ	±3μ	±300 μ
(Credition use)													
Processing size	400×500	300X400	300×400	300×400	300×400	150×150	300×400	150×150	300×400	300×400	300×400	300×400	150X150
(Max work)	*300X400												
unit mm													

Minimum pitch · L / S · Processing accuracy also depends on film thickness etc specifications.

We will help you create empty cells etc with thin glass laminating technology cultivated with glass / glass touch panel.

### ①Processing contents

- Glass + glass laminate (Can step cut)
- Glass + film lamination
   (Specification consultation necessary)

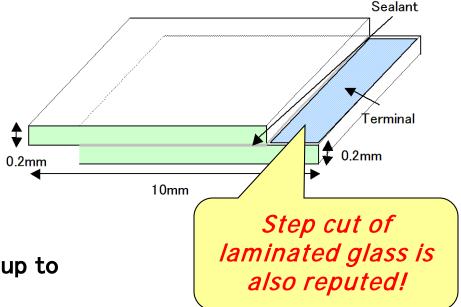
#### 2Processing size

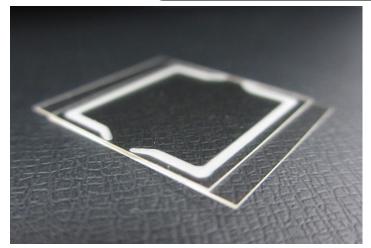
•MAX It is possible to process glass substrates up to 400 mm × 360 mm.

Thinness up / down 0.2mm ~Available G+F:(Specification consultation necessary)

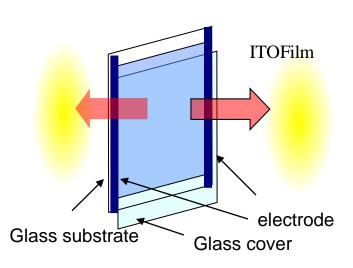
## 3 Machining record

•Gap between glass and glass:  $10\sim30\,\mu$  m (Bonding with sealing material)





## ITO heater processing





## [Application]

- •For dew condensation prevention of surveillance cameras and equipment requiring visibility
- Micro flow path etc Want to warm while observing Chemical analysis, for cell culture experiment!
- For aircraft and special vehicle monitors that require full LCD performance!
- To prevent fogging of the mirror in the bathroom and the washroom!

#### (Size)

- Minimum 10 mm × 10 mm to maximum 370 mm X
   470 mm (panel shape)
- -Minimum to maximum 300 φ (wafer shape)





## Assisting various materials evaluation



- · I would like you only to apply our own resist.
- Is there any place you can ask for exposure and development only?
- I would like to peel film from substrate!
- · I want to work in a clean room.
- I want to get a small glass as cheap as possible!

Techno print also responds to such troubles!

## Evaluation support for development of various materials

Process	apply of resist	Exposure Developing	etching	Cut	
Washing					
Apply of resist					
Pre bake					
Exposure					
Developing					
Post bake					
etching					
Peeling off					
Cut					
Chamfer					
Washing					
Inspection					
Packing					



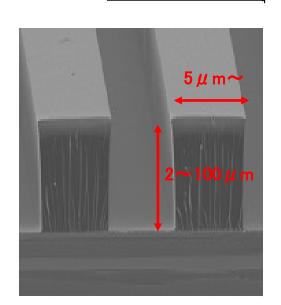












At TCN, we provide customized types of precision with various resist agents.

Pattern shape can be straight / circular (cylindrical)

Aspect ratio 5:1 (film thickness 50µm or more) possible, (3:1 actual results)



## Application example

- · Follow ability evaluation of adhesive, adhesive film, filler (semiconductor PKG etc.)
- · Micro folder such as micro LED
- · Cover glass spacer of solar cell etc.

In addition to simulation, evaluation and verification that is close to the actual machine is possible.

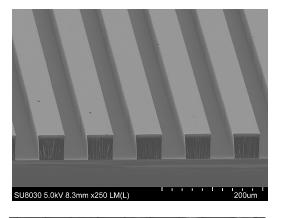
By creating a mask, it is possible to divide multiple shapes by changing the line width such as L shape, straight line, circular shape (cylindrical) etc. on the same board.

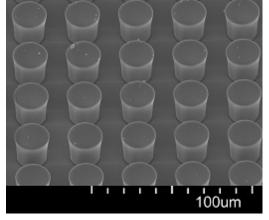
Aspect ratio 5: 1 (film thickness 50  $\mu$  m or more) possible, height 2 to 100  $\mu$  possible

\* However, the same height is on the same board. Substrate size is easy to use up to 300 mm in large format 

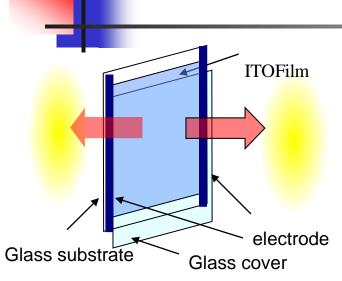
50, 100, 200 mm and any size can be cut. 

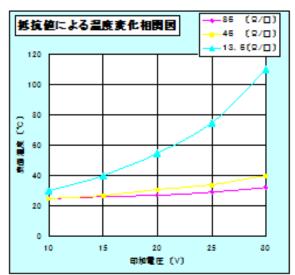
Glass / silicon wafers etc are possible as base material.





# ITO heater processing





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- For aircraft and special vehicle monitors that require full LCD performance!
- To prevent fogging of the mirror in the bathroom and the washroom!
- \* A wide FPC can also be crimped to 300 mm ACF!

### [Size]

- Minimum 10 mm × 10 mm to maximum 370 mm X
   470 mm (panel shape)
- -Minimum to maximum 300 φ (wafer shape)



## Light-sensitive resin patterning

- 1 The processing possible film kind
  - •Register, polyimide, resin black and exposure to light Ag (MAX170□) etc.
- 2 Processing size •MAX:300mm × 300mm

\*Effective area:  $\phi$  300mm

**3**Processing results

	Line	Space	
Resiser	$3\mu$ m	3 μ m	
Polyimide	<b>10</b> μ m	10 μ m	
Resin black	7 μ m	15 μ m	
Photosensitive Ag	<b>10</b> μ m	10 μ m	